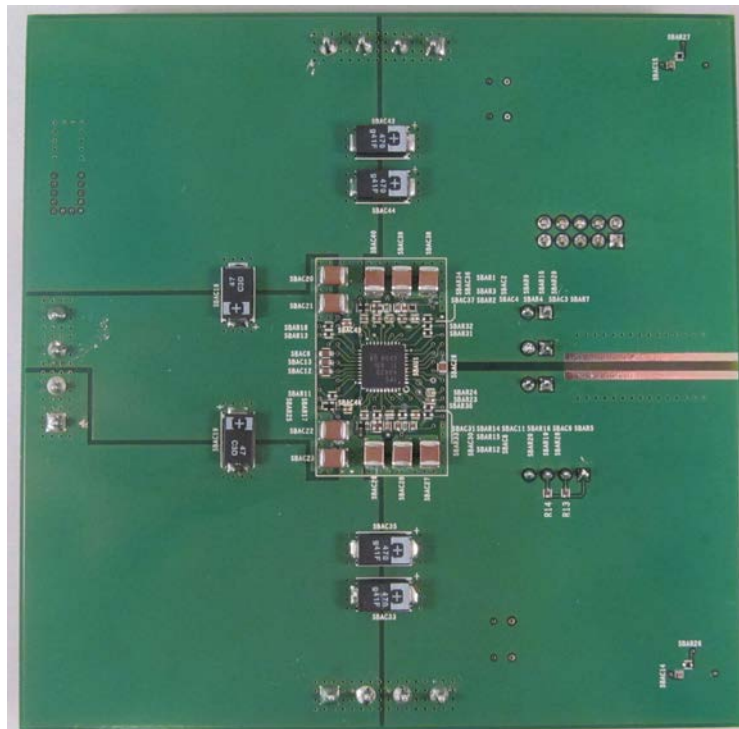
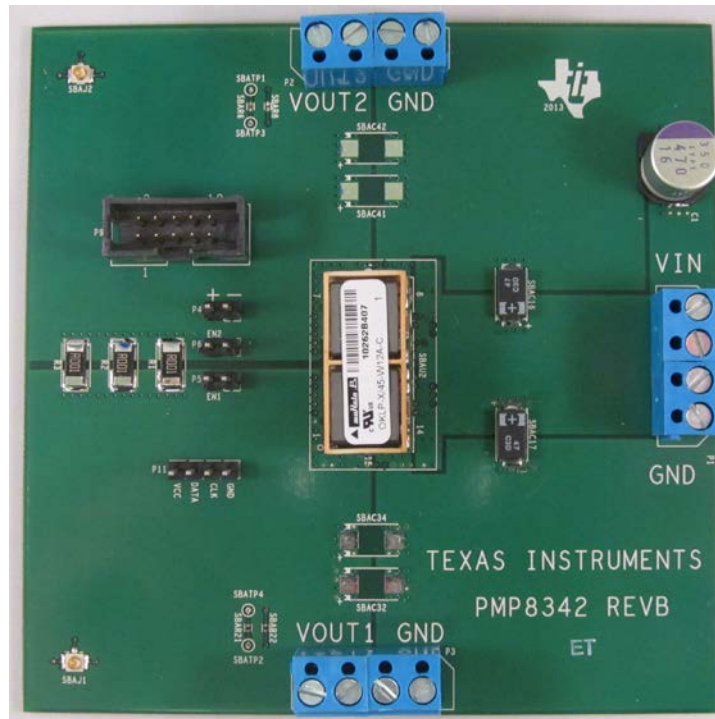
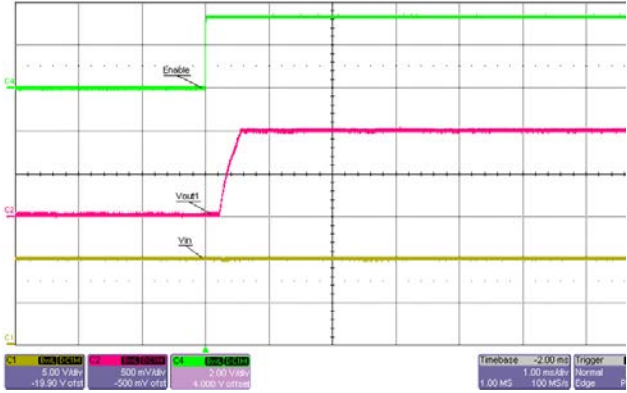


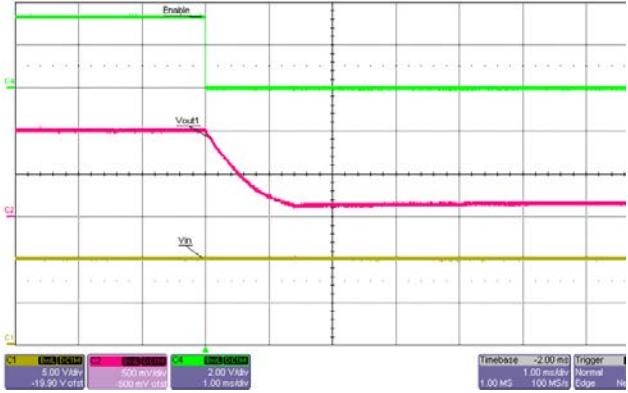
Photo of the prototype



1 Startup and shutdown

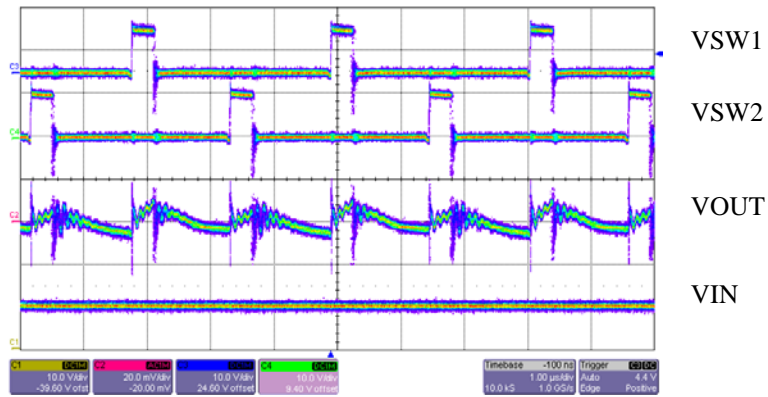


Turn-on, 10Vin, 1.0Vout



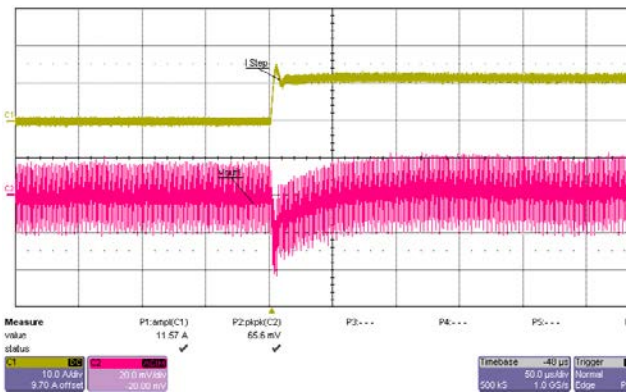
Turn-off, 10Vin, 1.0Vout

2 Ripple

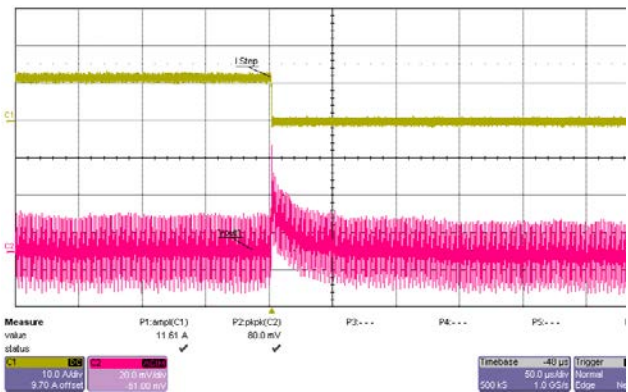


10Vin, 1.0Vout, 100% Load, SW1, SW2, Vin& Vout

3 Transient

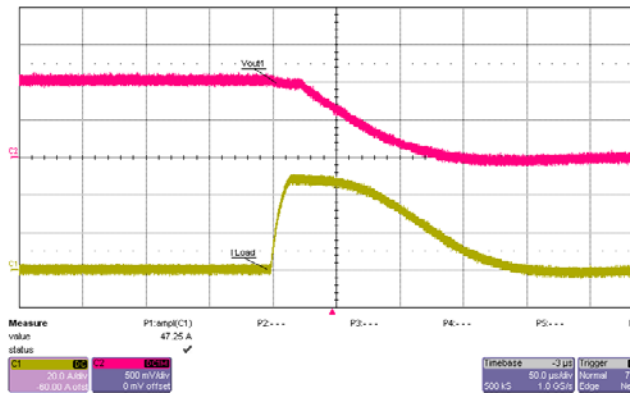


10Vin, 1.0Vout, 75% to 100% Load Step

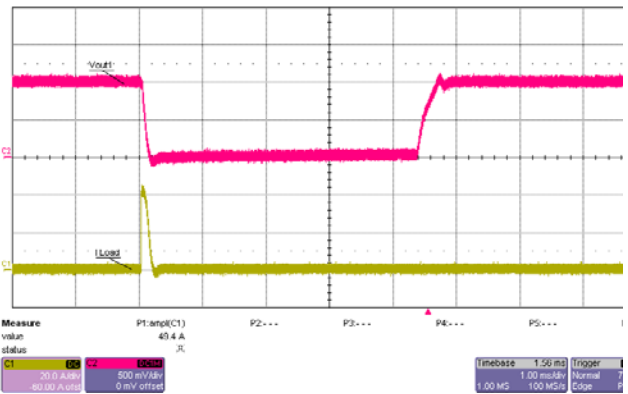


10Vin, 1.0Vout, 100% to 75% Load Step

4 Short-circuit protection

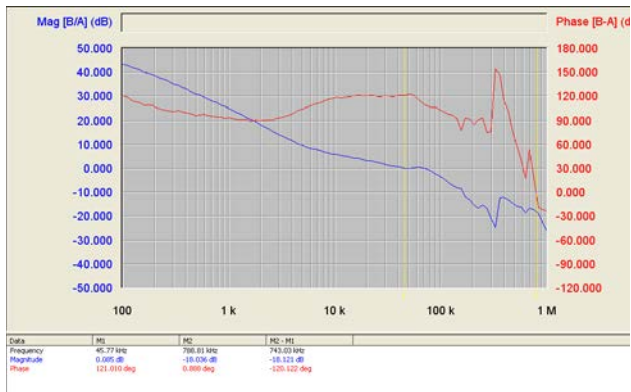


10Vin, 1.0Vout, Short circuit applied

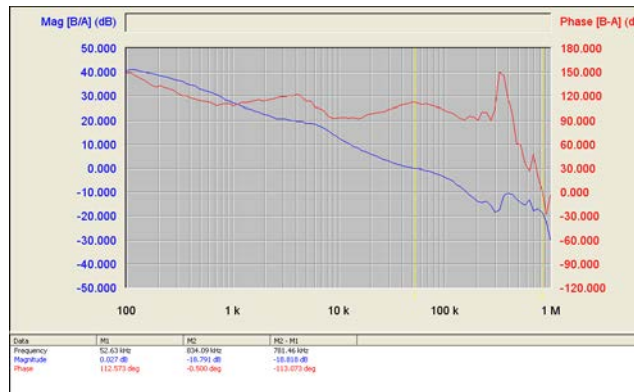


10Vin, 1.0Vout, Short circuit released

5 Bode Plot

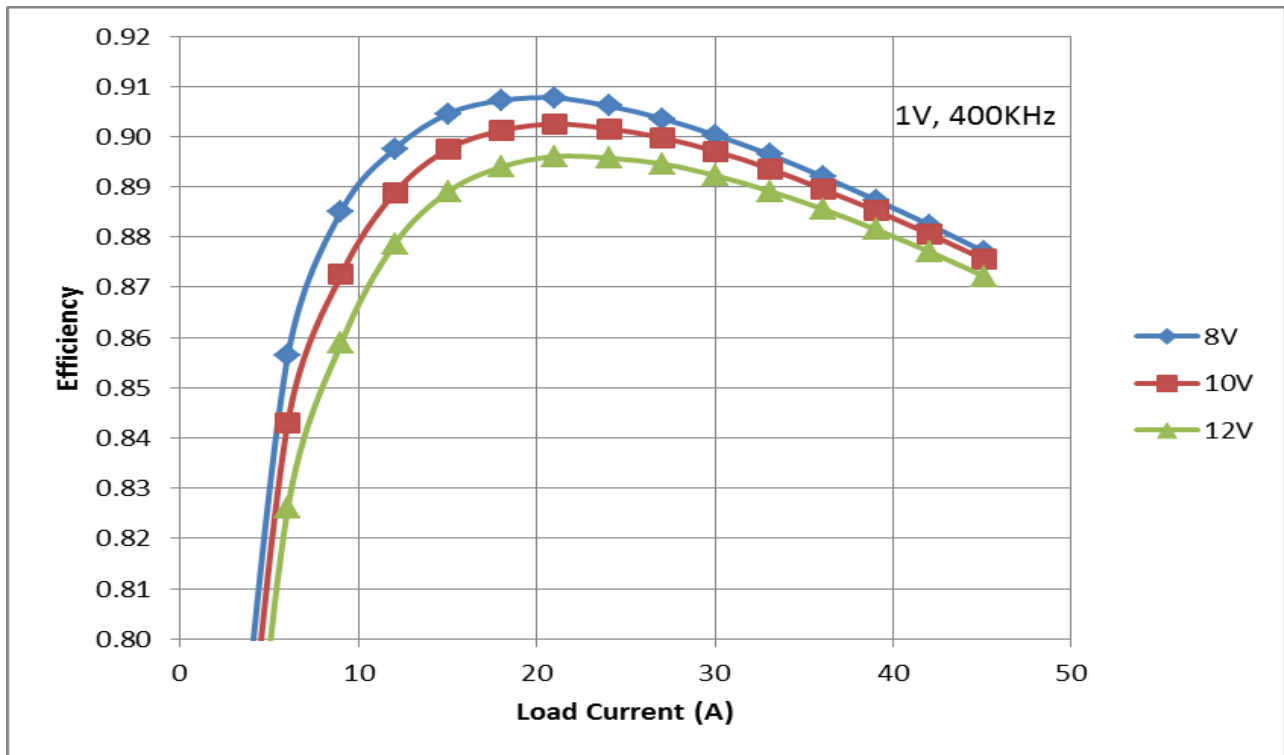


10Vin, 1.0Vout, 10% Load, BW=45.8kHz, PM=121deg, GM=18dB

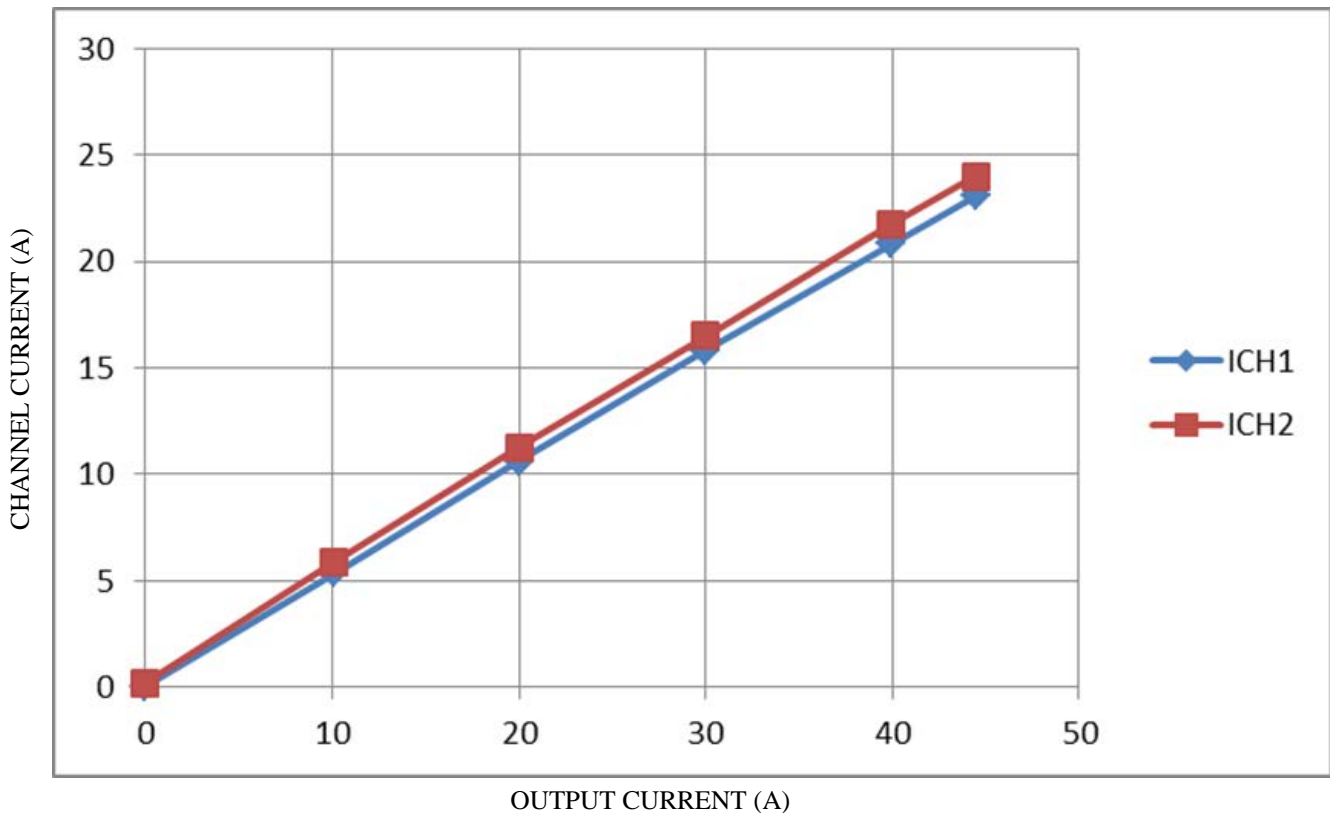


10Vin, 1.0Vout, 100% Load, BW=52.6kHz, PM=113deg, GM=18.8dB

6 Efficiency



7 Current Report



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